

SN54279, SN54LS279A, SN74279, SN74LS279A QUADRUPLE S-R LATCHES

SDLS093 – DECEMBER 1983 – REVISED MARCH 1988

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs

- Dependable Texas Instruments Quality and Reliability

description

The '279 offers 4 basic \bar{S} - \bar{R} flip-flop latches in one 16-pin, 300-mil package. Under conventional operation, the \bar{S} - \bar{R} inputs are normally held high. When the \bar{S} input is pulsed low, the Q output will be set high. When \bar{R} is pulsed low, the Q output will be reset low. Normally, the \bar{S} - \bar{R} inputs should not be taken low simultaneously. The Q output will be unpredictable in this condition.

FUNCTION TABLE
(each latch)

INPUTS		OUTPUT
\bar{S}^\dagger	\bar{R}	Q
H	H	Q_0
L	H	H
H	L	L
L	L	H^\ddagger

H = high level L = low level

† For latches with double S inputs:

Q_0 = the level of Q before the indicated input conditions were established.

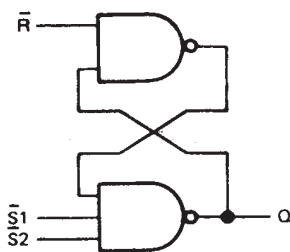
‡ This configuration is nonstable: that is, it may not persist when the \bar{S} and \bar{R} inputs return to their inactive (high) level.

H = both \bar{S} inputs high

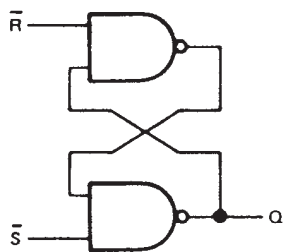
L = one or both \bar{S} inputs low

logic diagram (positive logic)

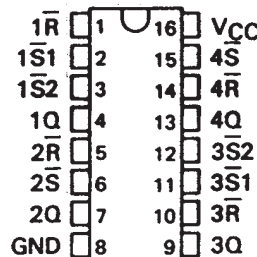
(latches 1 and 3)



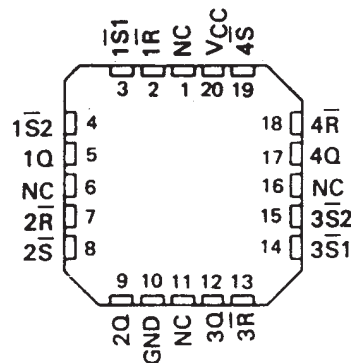
(latches 2 and 4)



SN54279, SN54LS279A . . . J OR W PACKAGE
SN74279 . . . N PACKAGE
SN74LS279A . . . D OR N PACKAGE
(TOP VIEW)

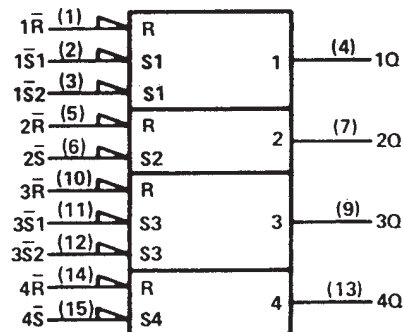


SN54LS279A . . . FK PACKAGE
(TOP VIEW)



NC - No internal connection

logic symbol[§]



[§]This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 1988, Texas Instruments Incorporated

SN54279, SN54LS279A, SN74279, SN74LS279A QUADRUPLE S-R LATCHES

SDLS093 – DECEMBER 1983 – REVISED MARCH 1988

recommended operating conditions

	SN54279			SN74279			UNIT		
	MIN	NOM	MAX	MIN	NOM	MAX			
V _{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V		
V _{IH} High-level input voltage	2			2			V		
V _{IL} Low-level input voltage	0.8			0.8			V		
I _{OH} High-level output current	-0.8			-0.8			mA		
I _{OL} Low-level output current	16			16			mA		
t _w Pulse duration, low	20			20			ns		
T _A Operating free-air temperature	-55			125			0	70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54279			SN74279			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V _{IK}	V _{CC} = MIN, I _I = -12 mA	-1.5			-1.5			V
V _{OH}	V _{CC} = MIN, V _{IL} = 0.8 V, I _{OH} = -0.8 mA	2.4	3.4		2.4	3.4		V
V _{OL}	V _{CC} = MIN, V _{IH} = 2 V, I _{OL} = 16 mA	0.2	0.4		0.2	0.4		V
I _I	V _{CC} = MAX, V _I = 5.5 V	1			1			mA
I _{IH}	V _{CC} = MAX, V _I = 2.4 V	40			40			μA
I _{IL}	V _{CC} = MAX, V _I = 0.4 V	-1.6			-1.6			mA
I _{OS} §	V _{CC} = MAX	-18		-55	-18		-57	mA
I _{CC}	V _{CC} = MAX, See Note 2	18		30	18		30	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

§ Not more than one output should be shorted at a time.

NOTE 2: I_{CC} is measured with all R inputs grounded, all S inputs at 4.5 V, and all outputs open.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _{PLH}	\bar{S}	Q	R _L = 400 Ω, C _L = 15 pF		12	22	ns
t _{PHL}	S	Q			9	15	
t _{PHL}	\bar{R}	Q			15	27	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

SN54279, SN54LS279A, SN74279, SN74LS279A QUADRUPLE S-R LATCHES

SDLS093 – DECEMBER 1983 – REVISED MARCH 1988

recommended operating conditions

	SN54LS279A			SN74LS279A			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V _{IH} High-level input voltage	2			2			V
V _{IL} Low-level input voltage			0.7			0.8	V
I _{OH} High-level output current			-0.4			-0.4	mA
I _{OL} Low-level output current			4			8	mA
t _w Pulse duration, low	20			20			ns
T _A Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54LS279A			SN74LS279A			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V _{IK}	V _{CC} = MIN, I _I = -18 mA			-1.5			-1.5	V
V _{OH}	V _{CC} = MIN, V _{IL} = MAX, I _{OH} = -0.4 mA	2.5	3.4		2.7	3.4		V
V _{OL}	V _{CC} = MIN, V _{IH} = 2 V, I _{OL} = 4 mA		0.25	0.4		0.25	0.4	V
	V _{CC} = MIN, V _{IH} = 2 V, I _{OL} = 8 mA					0.25	0.5	
I _I	V _{CC} = MAX, V _I = 7 V			0.1			0.1	mA
I _{IH}	V _{CC} = MAX, V _I = 2.7 V			20			20	μA
I _{IL}	V _{CC} = MAX, V _I = 0.4 V			-0.2			-0.2	mA
I _{OS} §	V _{CC} = MAX	-20		-100	-20		-100	mA
I _{CC}	V _{CC} = MAX, See note 2		3.8	7		3.8	7	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

§ Not more than one output should be shorted at a time, and the duration of the short-circuit should be less than one second.

NOTE 2: I_{CC} is measured with all R inputs grounded, all S inputs at 4.5 V, and all outputs open.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _{PLH}	S	Q	R _L = 2 kΩ, C _L = 15 pF		12	22	ns
t _{PHL}					13	21	
t _{PHL}	R	Q			15	27	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
76018012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
7601801EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
7601801EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
7601801FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
7601801FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SN54279J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN54279J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN54LS279AJ	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS279AJ	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN74279N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74279N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74279N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74279N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS279AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS279AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS279ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS279ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS279ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS279ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS279ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS279ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS279AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS279AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS279AN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS279AN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS279ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS279ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS279ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS279ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS279ANSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS279ANSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SNJ54279J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SNJ54279J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SNJ54279W	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI
SNJ54279W	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI
SNJ54LS279AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS279AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS279AJ	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS279AJ	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS279AW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS279AW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

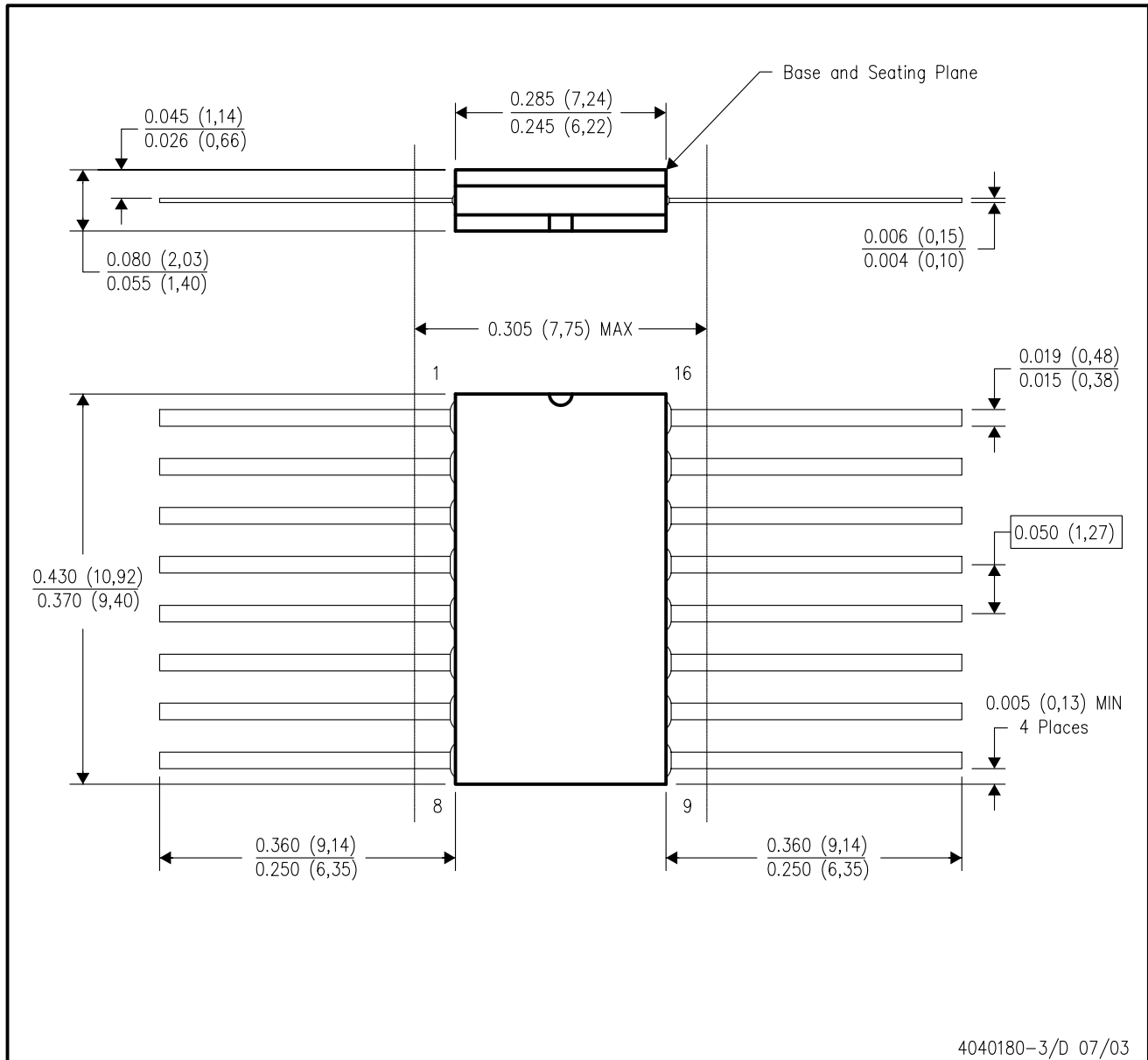


4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

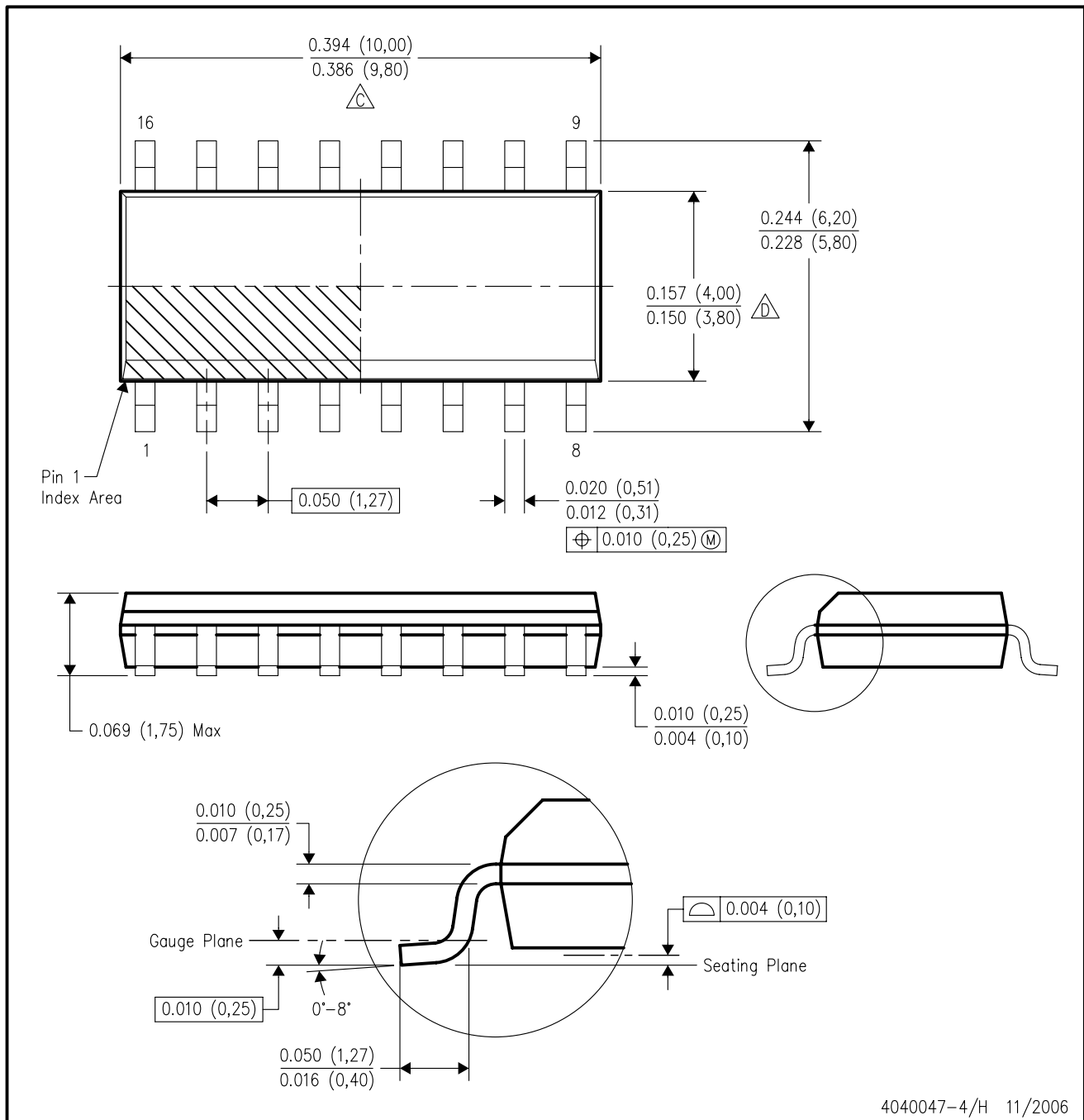
16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AC.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DSP	dsp.ti.com
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
Low Power Wireless	www.ti.com/lpw

Applications

Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments
Post Office Box 655303 Dallas, Texas 75265